Sheet 1

Docket Number (Optional)
SAM-0313

Application Number (Optional)
SAM-0313

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Applicant
Soo-geun Lee, et al.

Filling Date
2-22-02

U. S. Patent Documents

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	AL								
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EXAMINER					DATE CONSIDERED 3 -12-4				

through citation if not in conformance and not considered. Include copy with next communication to applicant.

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